Construction

SikaBond®-T53

High viscous elastic adhesive for wood flooring

Product Description

SikaBond®-T53 is a one part, elastic adhesive.

Uses

For the Sika® AcouBond®-System:

- Solid wood boards (tongued and grooved), 3-ply engineered wood as well as chipboards can all be bonded
- For detailed application instructions consult the Product Data Sheet of the Sika® AcouBond®-System, or contact our Technical Service.

For beaded Application:

- Solid wood boards (tongued and grooved), 3-ply engineered wood as well as chipboards can be bonded
- Elastic Bonding of skirting boards / baseboards and thresholds

Characteristics / Advantages

- 1-part, ready to use
- Fast curing
- Elastic, footfall-sound-dampening adhesive
- Suitable for common types of wood floors
- Especially for problematic wood such as beech and bamboo
- Suitable for bonding wood floors directly onto old ceramic tiles
- Reduces stress on the substrate: the elastic, material-compatible adhesive reduces transverse stress between the wood floor and the substrate
- Compensation of small substrate unevenness
- Suitable for subfloor heating
- Adhesive can be sanded

Product Data

Form

Colour	Parquet brown
Packaging	600 ml sausages (20 sausages per box)

Storage

Storage Conditions / Shelf Life	12 months from date of production if stored in undamaged original sealed containers, in dry conditions and protected from direct sunlight at temperatures between +10°C and +25°C.

Technical Data

Chemical Base	1-part Polyurethane, moisture curing	
Density	~ 1.2 kg/l	(According to DIN 53 479)
Skinning- / Laying Time	~ 45 - 60 minutes (+23°C / 50% r.h.)	
Curing Rate	~ 3.0 mm / 24h (+23°C / 50% r.h.) Floor may be walked on / sanded 18 - 42 hours after installation (depending on climatic conditions and adhesive layer thickness).	
Sag Flow	Consistency: Easily applicable with gun, thixotropic.	
Service Temperature	-40°C to +70°C	

Mechanical / Physical Properties

Shear Strength	~ 1.2 N/mm^2, 1 mm adhesive thickness (+23°C / 50% r.h.)	(According to DIN 281)
Tensile Strength	~ 1.8 N/mm^2 (+23°C / 50% r.h.)	(According to DIN 53 504)
Shore A Hardness	~ 40 (after 28 days)	(According to DIN 53 505)
Elongation at Break	~ 500% (+23°C / 50% r.h.)	(According to DIN 53 504)

System Information

Application Details

Consumption	Sika® AcouBond-System: 580 (03) - 720 (05) g/m^2 (480 - 600 ml/m^2). Filling of all cut-outs is a must. Use triangular nozzle with 8x10 mm opening. Cordon Application: Approx. 44 ml per running meter = 200 - 400 g/m^2, dependent on cordon interval (solid wood boards, 3-ply engineered wood, chipboards).
Substrate Quality	Clean and dry, homogeneous, even, free from grease, dust and loose particles. Paint, laitance and other poorly adhering particles must be removed. Standard construction rules must be observed.
Substrate Preparation	Concrete / cement screed*:* Must be ground and thoroughly cleaned with industrial vacuum cleaner. Anhydrite screed / Anhydrite flowable screed*:* Must be ground and thoroughly cleaned with industrial vacuum cleaner shortly before bonding starts. Broadcast mastic asphalt*:* Must be primed with Sika® Primer MB. Instructions for use, see Product Data Sheet for Sika® Primer MB. Glazed ceramic and old ceramic tiles*:* Degrease, clean with SikaCleaner® or grind the tile-surface and clean thoroughly with an industrial vacuum cleaner. Wood- / gypsum boards (e.g. chipboards, plywood)*:* Glue / screw the boards to the substructure. They have to be fixed on the substrate. In case of floating subfloors, please contact our Technical Service. Unknown substrates*:* Please contact our Technical Service. SikaBond®-T53 can be used without priming on cement floors, anhydrite floors, chip boards, concrete and ceramic tiles. For broadcast mastic asphalt, cement floors with an excessive moisture content, as well in case of renovation on old adhesive residues and on structurally weak substrates use Sika® Primer MB. For detailed instructions consult the Product Data Sheet of Sika® Primer MB or contact our Technical Service.

Application Conditions / Limitations

Substrate Temperature	During laying and until SikaBond®-T53 has fully cured substrate temperature must be > +15°C and in case of floor heating < +20°C. For Substrate temperatures the standard construction rules are relevant
Ambient Temperature	Room temperature between +15°C and +35°C. For ambient temperatures the standard construction rules are relevant.
Substrate Moisture Content	Permissible substrate moisture content: - 2.5% CM for cement screed (ca. 4% Tramex / Gravimetric weight percent) - 0.5% CM for anhydrite screed - 3-12% CM for magnesia flooring (proportion of organic parts) Permissible substrate moisture content in case of floor heating: - 1.8% CM for cement screed (ca. 3% Tramex / Gravimetric weight percent) - 0.3% CM for anhydrite screed - 3-12% CM for magnesia flooring (proportion of organic parts) For moisture content and quality of substrates the guidelines of wood floor manufacturer as well as standard construction rules must be observed.
Relative Air Humidity	Between 40% and 70%

Application Instructions

Application Method / Tools	Sika® AcouBond®-System: For detailed application instructions consult the Product Data Sheet of the Sika® AcouBond®-System, or contact our Technical Service. Cordon Application: After the preparation of sausage and gun, extrude a triangular shaped cordon of adhesive approximately 10 mm high and 8 mm wide at 100-250 mm centres (dependent on wood floor type) on the properly prepared subfloor. Press the wood floor elements firmly in to the adhesive (at right angles with adhesive cordons). The elements can then be joined together using a hammer and a impact block. The required distance from the wall to the wood floor in the laying instruction from the wood floor manufacturer must be observed. Fresh, uncured adhesive remaining on the wood floor surface must be removed immediately with a clean cloth and if necessary cleaned with Sika® Remover-208 or Sika® TopClean-T towels. Test wood floor surfaces for compatibility before use. The laying instructions of the wood floor manufacturer as well as standard construction rules must be observed.
Cleaning of Tools	Clean all tools and application equipment with Sika® Remover-208 / Sika® TopClean-T immediately after use. Hardened / cured material can only be removed mechanically.

Construction

Notes on Application / Limitations

Wood floor adhesives must only be used by expirienced applicators.

If, according to wood floor suppliers or producers deviation from the standards is permissible, temperatures between +5°C and +35°C must be observed for the adhesive.

For better workability the adhesive temperature must be at least +15°C.
For the proper curing of the adhesive sufficient ambient moisture is necessary.

For AcouBond-System and Cordon Application accurate tongue and groove (min. 3x3 mm) are inevitable:

Minimum wood size:	length	> 300 mm (over 3 adhesive cordons)
	width	> 50 mm
	thickness	> 12 mm
Maximum wood size:	thickness	< 28 mm

Wood floors in non insulated areas such as basements, or other areas without a damp proof membrane, can only be installed after the application of Sikafloor® EpoCem and Sika® Primer MB to control the moisture. For detailed instructions consult the Product Data Sheets or contact our Technical Service.

In case of chemically pre-treated types of wood floors (e.g. ammonia, wood stain, timber preservative) and woods with high oil content SikaBond®-T53 is only to be used after a written recommendation from our Technical Service.

Do not use on PE, PP, TEFLON, and certain plastizied synthetic materials (carry out pre-trials or contact our Technical Service).

Some primers can negatively influence the adhesion of SikaBond®-T53 (pre trials recommended).

When laying bonded wood flooring, always make sure that any wood surface sealer coatings do not come into contact with the adhesive. However if direct contact with the adhesive is unavoidable, then the compatibility of the sealing coats must always be checked and confirmed before use. For further information or assistance please contact your local Sika Technical Service Department.

Do not mix with or expose uncured SikaBond®-T53 to substances that may react with isocyanates, especially alcohols which are often components within e.g. thinners, solvents, cleaning agents and formwork releasing compounds. Such contact could interfere or prevent the cross linking curing reaction of the material.

Value Base

All technical data stated in this Product Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

Health and Safety Information

For information and advice on the safe handling, storage and disposal of chemical products, users shall refer to the most recent Material Safety Data Sheet containing physical, ecological, toxicological and other safety-related data.

Legal Notes

Sika India Pvt. Ltd.
Commercial Complex II
620, Diamond Harbour Road
Kolkata, 700 034, India

Phone +91 33 2447 2448/2449
Telefax +91 33 2468 8688/2665
www.sika.in
info@in.sika.com